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Announcement

PNS ON SEMICONDUCTOR DEVICES

The Department of Trade and Industry's Bureau of Product Standards (DTI-BPS) informs the concerned sectors that the following standards have been adopted as PNS.

The DTI-BPS adopts these standards through the fast tract method.

PNS IEC 60749-19:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 19: Die shear strength (IEC published 2010) ICS [31.080.01](#)

PNS IEC 60749-20-1:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat (IEC published 2009) ICS 31.080.01

PNS IEC 60749-20:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat (IEC published 2008) ICS 31.080.01

PNS IEC 60749-21:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 21: Solderability (IEC published 2011) ICS 31.080.01

PNS IEC 60749-22:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 22: Bond strength (IEC published 2002) ICS 31.080.01

PNS IEC 60749-23:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 23: High temperature operating life (IEC published 2011) ICS 31.080.01

PNS IEC 60749-24:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbiased HAST (IEC published 2004) ICS 31.080

PNS IEC 60749-25:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 25: Temperature cycling (IEC published 2003) ICS 31.080.01

PNS IEC 60749-26:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM) (IEC published 2013) ICS 31.080.01

PNS IEC 60749-27:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 27: Electrostatic discharge (ESD) sensitivity testing - Machine model (MM) (IEC published 2012) ICS 31.080.01

PNS IEC 60749-31:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 31: Flammability of plastic-encapsulated devices (internally induced) (IEC published 2002) ICS 31.080.01

PNS IEC 60749-32:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-encapsulated devices (externally induced) (IEC published 2010) ICS 31.080.01

PNS IEC 60749-33:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 33: Accelerated moisture resistance - Unbiased autoclave (IEC published 2004) ICS 31.080

PNS IEC 60749-35:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 35: Acoustic microscopy for plastic encapsulated electronic components (IEC published 2006) ICS 31.080.01

PNS IEC 60749-36:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 36: Acceleration, steady state (IEC published 2003) ICS 31.080.01

PNS IEC 60749-37:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 37: Board level drop test method using an accelerometer (IEC published 2008) ICS 31.080.01

PNS IEC 60749-38:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 38: Soft error test method for semiconductor devices with memory (IEC published 2008) ICS 31.080.01

PNS IEC 60749-39:2013 - Semiconductor devices - Mechanical and climatic test methods - Part 39: Measurement of moisture diffusivity and water solubility in organic materials used for semiconductor components (IEC published 2006) ICS 31.080.01

Copies of the standard can be purchased from the BPS Standards Data Centre at 751.4736.

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- International Organization for Standardization (ISO)
- Enquiry Point for WTO Technical Barriers to Trade (WTO-TBT)